

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2022/0360230 A1 Marbell et al.

Nov. 10, 2022 (43) Pub. Date:

(54) **OUTPUT-INTEGRATED TRANSISTOR** AMPLIFIER DEVICE PACKAGES INCORPORATING INTERNAL CONNECTIONS

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(21) Appl. No.: 17/313,567

(22) Filed: May 6, 2021

Publication Classification

(51) Int. Cl. H03F 1/02 (2006.01)H03F 1/56 (2006.01)H01L 23/66 (2006.01)(2006.01) H01L 23/498

(52) U.S. Cl. H03F 1/0288 (2013.01); H03F 1/565 CPC (2013.01); H01L 23/66 (2013.01); H01L 23/49838 (2013.01); H01L 2223/6611

(2013.01); H01L 2223/6655 (2013.01)

(57)ABSTRACT

A semiconductor device package includes a plurality of input leads and an output lead, a plurality of transistor amplifier dies having inputs respectively coupled to the plurality of input leads, and a combination circuit configured to combine output signals received from the plurality of transistor amplifier dies and output a combined signal to the output lead.

